Hyper SuperServer SYS-621H-TN12R

More details here

Key Applications

Virtualization, Software-defined Storage, AI Inference and Machine Learning, Cloud Computing, Enterprise Server,

Key Features

- Dual Socket E (LGA-4677) 4th Gen Intel® Xeon® Scalable processors;
- 32 DIMM slots supporting up to 8TB of memory; RDIMMs up to DDR5-4800;
- Optional PCIe slot configurations up to 8 PCIe 5.0 x8 or 4 PCIe 5.0 x16 slots with support for double-width GPU/Accelerator cards;
- Flexible networking options with up to 2 AIOM networking slots (OCP NIC 3.0 compatible);
- 12x 3.5"/2.5" hot-swap NVMe/SATA/SAS drive bays; 2x internal M.2 NVMe/SATA drive slots; Optional RAID support via storage add-on card;
- 4 heavy duty hot-swap fans with optimal fan speed control;

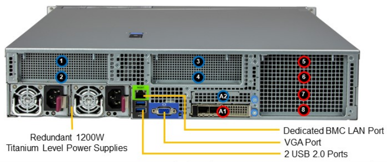
Form Factor	2U Rackmount Enclosure: 437 x 88.9 x 803mm (17.2" x 3.5" x 31.6") Package: 605 x 263 x 1107mm (23.8" x 10.4" x 43.6")
Processor	4th Gen Intel® Xeon® Scalable processors Dual Socket LGA-4677 (Socket E) supported 4 UPI Intel Xeon CPU Max Series with high bandwidth memory (HBM) (Supports up to 350W TDP CPUs (Air-Cooled), Supports up to 350W TDP CPUs (Liquid-Cooled))
System Memory	32 DIMM slots Up to 8TB ECC RDIMM, DDR5-4800MHz
Drive Bays	12x 3.5" hot-swap NVMe/SATA/SAS drive bays 2 M.2 NVMe OR 2 M.2 SATA3 M-Key, 2280/2210
Expansion Slots	4 (Optional) PCIe 5.0 x16 or x8 FH, 10.5"L slot(s) 4 (Optional) PCIe 5.0 x8 FH, 10.5"L slot(s)
On-Board Devices	SATA: SATA3 (6Gbps); RAID 0/1/5/10 support NVMe: NVMe; RAID 0/1/5/10 support (Intel® VROC RAID Key required) Chipset: Intel® C741 Network Connectivity: 2x 1GbE BaseT with Intel® i350-AM2 (optional) 4x 1GbE BaseT or 4x 1GbE SFP with Intel® i350-AM4 (optional) 2x 10GbE BaseT with Intel® X550-AT2 (optional) 2x 10GbE SFP+ with Intel® X710-BM2 (optional) 4x 10GbE SFP+ with Intel® XL710-BM1 (optional) 4x 10GbE RJ45/SFP+ with Intel® X710-TM4 (optional) 2x 25GbE SFP28 with Broadcom® BCM57414 (optional) 4x 25GbE RJ45/SFP28 with Mellanox® CX-4 Lx EN Intel® X550-AT2 (optional) 2x 100GbE QSFP28 with Broadcom® BCM57508 (optional) IPMI: Support for Intelligent Platform Management Interface v.2.0 IPMI 2.0 with virtual media over LAN and KVM-over-LAN support
Input / Output	LAN: 1 RJ45 Dedicated BMC LAN port USB: 2 USB 2.0 port(s) (2 rear) Video: 1 VGA port(s)

(Front View – System)

Slot	Description
0 – 5	3.5" or 2.5" Hot-swap NVMe/SAS3/SATA3 Drive Bays (NVMe from CPU1)*
6 – 11	3.5" or 2.5" Hot-swap NVMe/SAS3/SATA3 Drive Bays (NVMe from CPU2)*

*NVMe, SAS3, or SATA3 support requires additional parts from the optional parts list

(Rear View – System)



	Slot Description		
	Option 1[1]	Option 2[1]	Option 3[1,2]
1	PCIe 5.0 x8 (in x16)	PCIe 5.0 x16	2x Hot-Swap 2.5" NVMe Drive Bays (CPU 2)
2	PCIe 5.0 x8 (in x16)	---	

	Slot Description		
	Option 1[1]	Option 2[1]	Option 3[1,2]
3	PCIe 5.0 x8 (in x16)	PCIe 5.0 x16	2x Hot-Swap 2.5" NVMe Drive Bays (CPU 2)
4	PCIe 5.0 x8 (in x16)	---	

[1] Requires additional parts in optional parts list

[2] Not available if front drive bays are using an NVMe configuration

	Slot Description		
	Option 1[1]	Option 2[1]	Option 3[1]
5	PCIe 5.0 x8 (in x16)	PCIe 5.0 x16	PCIe 5.0 x16
6	PCIe 5.0 x8 (in x16)	---	---
7	PCIe 5.0 x8 (in x16)	PCIe 5.0 x8 (in x16)	PCIe 5.0 x16
8	PCIe 5.0 x8 (in x16)	PCIe 5.0 x8 (in x16)	---

	Slot Description
A1	AIOM / OCP NIC 3.0 Slot
A2	(Optional) AIOM / OCP NIC 3.0 Slot[1]

CPU1 🟥 CPU2 🟦

System Cooling	4x 8cm heavy duty fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	1U 800W/1200W Redundant Titanium CRPS w/PMBus power supply Dimension (W x H x L): 73.5 x 40 x 265 mm Output Type: 25 Pairs Gold Finger Connector
System BIOS	BIOS Type: AMI 256MB SPI Flash
Management	SuperDoctor® 5; Watch Dog; NMI; SUM; KVM with dedicated LAN; SPM; Intel® Node Manager; SSM; IPMI 2.0; Redfish API
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Status monitor for speed control Pulse Width Modulated (PWM) fan connectors Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Height: 3.5" (88.9 mm) Width: 17.2" (437 mm) Depth: 31.6" (803 mm) Gross Weight: 63 lbs (28.6 kg) Net Weight: 37 lbs (16.8 kg) Packaging: 10.4" (H) x 23.8" (W) x 43.6" (D) Available Color: N/A
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F) Non-operating Temperature: -40°C to 70°C (-40°F to 158°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)
Motherboard	Super X13DEM
Chassis	CSE-HS829-R1K24P